

14-bit 12MSPS CIS/CCD Analogue Front End/Digitiser

DESCRIPTION

The WM8195 is a 14-bit analogue front end/digitiser IC which processes and digitises the analogue output signals from CCD sensors or Contact Image Sensors (CIS) at pixel sample rates of up to 12MSPS.

The device includes three analogue signal processing channels each of which contains Reset Level Clamping, Correlated Double Sampling and Programmable Gain and Offset Adjust functions. Three multiplexers allow single channel processing. The output from each of these channels is time multiplexed into a single high-speed 14-bit analogue-to-digital converter. The digital output data is available in 14-bit parallel or 8, 7 or 4-bit wide multiplexed data output format, with no missing codes.

An internal 4-bit DAC is supplied for internal reference level generation. This may be used during CDS to reference CIS signals or during Reset Level Clamping to clamp CCD signals. Alternatively an external reference level may be applied. ADC references are generated internally, ensuring optimum performance from the device.

Using an analogue supply voltage of 5V and a digital interface supply of either 5V or 3.3V, the WM8195 typically only consumes 210mW when operating from a single 5V supply and less than 20µA when in power down mode.

FEATURES

- 14-bit ADC
- No missing codes guaranteed
- 12MSPS conversion rate
- Low power – 210mW typical
- 5V single supply or 5V/3.3V dual supply operation
- Single or 3 channel operation
- Correlated double sampling
- Programmable gain (8-bit resolution)
- Programmable offset adjust (8-bit resolution)
- Programmable clamp voltage
- 14-bit parallel or 8, 7 or 4-bit wide multiplexed data output formats
- Internally generated voltage references
- 48-lead TQFP package
- Serial or parallel control interface

APPLICATIONS

- Flatbed and sheetfeed scanners
- USB compatible scanners
- Multi-function peripherals
- High-performance CCD sensor interface

BLOCK DIAGRAM

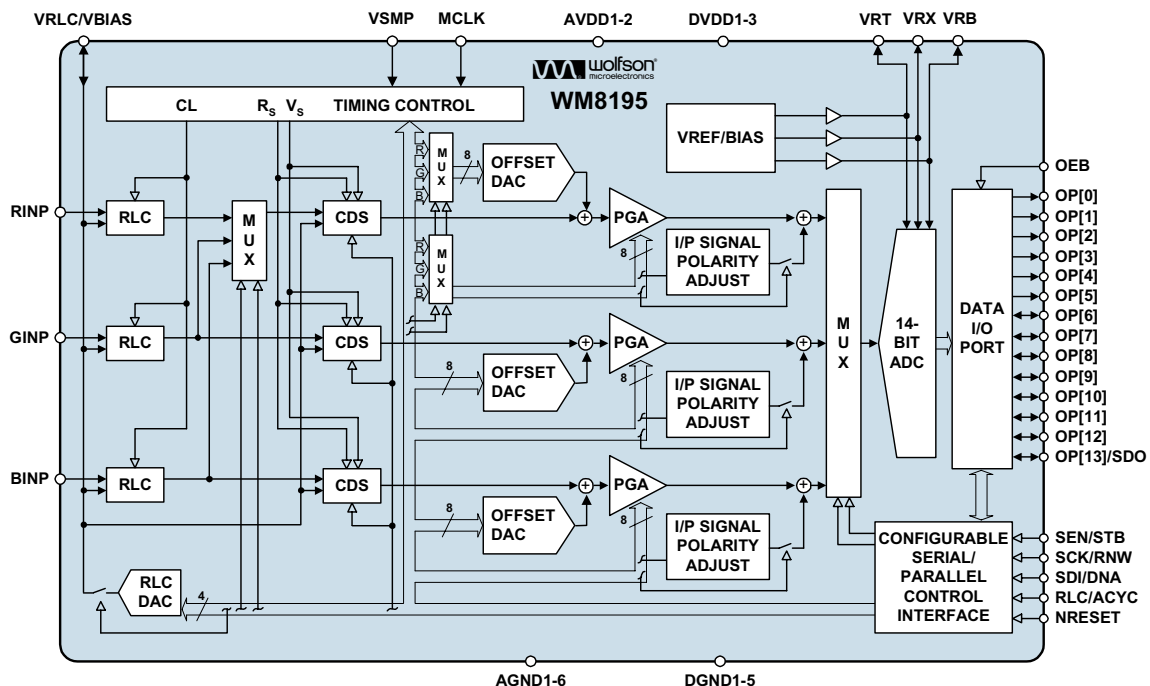
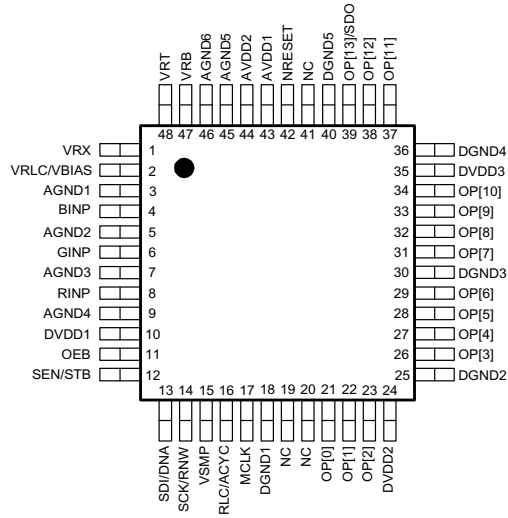


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PIN CONFIGURATION



ORDERING INFORMATION

DEVICE	TEMPERATURE RANGE	PACKAGE	MOISTURE SENSITIVITY LEVEL	PEAK SOLDERING TEMPERATURE
XWM8195SCFT/V	0 to 70°C	48-lead TQFP 1mm thick body (Pb-free)	MSL2	260°C
XWM81955CFT/RV	0 to 70°C	48-lead TQFP 1mm thick body (Pb-free, tape and reel)	MSL2	260°C

Note:

Reel quantity = 2,200

PIN DESCRIPTION

PIN	NAME	TYPE	DESCRIPTION
1	VRX	Analogue output	Input return bias voltage. This pin must be decoupled to AGND via a capacitor.
2	VRXC/VBIAS	Analogue I/O	Selectable analogue output voltage for RLC or single-ended bias reference. This pin would typically be decoupled to AGND via a capacitor. VRXC can be externally driven if programmed Hi-Z.
3	AGND1	Supply	Analogue ground (0V).
4	BINP	Analogue input	Blue channel input video.
5	AGND2	Supply	Analogue ground (0V).
6	GINP	Analogue input	Green channel input video.
7	AGND3	Supply	Analogue ground (0V).
8	RINP	Analogue input	Red channel input video.
9	AGND4	Supply	Analogue ground (0V).
10	DVDD1	Supply	Digital supply (5V) for logic and clock generator. This must be operated at the same potential as AVDD.
11	OEB	Digital input	Output Hi-Z control, all digital outputs disabled when OEB = 1.
12	SEN/STB	Digital input	Serial interface: enable pulse, active high Parallel interface: strobe, active low Latched on NRESET rising edge: if Low then device control is via serial interface, if high then device control is via parallel interface.
13	SDI/DNA	Digital input	Serial interface: serial input data signal Parallel interface: High = data, Low = address
14	SCK/RNW	Digital input	Serial interface: serial clock signal Parallel interface: High: OP[13:6] is output bus. Low: OP[13:6] is input bus (Hi-Z).
15	VSMP	Digital input	Video sample synchronisation pulse.
16	RLC/ACYC	Digital input	RLC (active high) selects reset level clamp on a pixel-by-pixel basis – tie high if used on every pixel. ACYC autocycles between R, G, B inputs when in Line-by-Line mode.
17	MCLK	Digital input	Master clock. This clock is applied at N times the input pixel rate (N = 2, 3, 6, 8 or any multiple of 2 thereafter depending on input sample mode).
18	DGND1	Supply	Digital ground (0V).
19	NC		No connection.
20	NC		No connection.
21	OP[0]	Digital output	Pins OP[13:0] form a Hi-Z digital bi-directional bus. There are several modes: Hi-Z: when OEB = 1. 14-bit output: 14-bit data is output on OP[13:0]. 8-bit multiplexed output: data is output on OP[13:6] at 2 * ADC conversion rate. 7-bit multiplexed output: data is output on OP[13:6] at 2 * ADC conversion rate. 4-bit multiplexed output: data is output on OP[13:10] at 4 * ADC conversion rate. See Output Formats section in Device Description for further details. Input 8-bit: control data is input on OP[13:6] in parallel mode when SCK/RNW = 0, and SEN/STB = 0. Output 8-bit: register read back data is output in parallel on OP[13:6] when SCK/RNW = 1, and SEN/STB = 0, or in serial on pin SDO when SEN/STB = 1.
22	OP[1]	Digital output	
23	OP[2]	Digital output	
24	DVDD2	Supply	
25	DGND2	Supply	Digital ground (0V).
26	OP[3]	Digital output	See pins 21 to 23 for details.
27	OP[4]	Digital output	
28	OP[5]	Digital output	
29	OP[6]	Digital I/O	
30	DGND3	Supply	

PIN	NAME	TYPE	DESCRIPTION
31	OP[7]	Digital I/O	See pins 21 to 23 for details.
32	OP[8]	Digital I/O	
33	OP[9]	Digital I/O	
34	OP[10]	Digital I/O	
35	DVDD3	Supply	Digital I/O supply (3.3V/5V).
36	DGND4	Supply	Digital ground (0V).
37	OP[11]	Digital I/O	See pins 21 to 23 for details.
38	OP[12]	Digital I/O	If the device has been configured to use the serial interface, pin OP[13]/SDO may be used to output register read-back data when OEB = 0 and SEN has been pulsed high. See Serial Interface sections in Device Description for further details.
39	OP[13]/SDO	Digital I/O	
40	DGND5	Supply	Digital ground (0V).
41	NC		No connection.
42	NRESET	Digital input	Reset input, active low. This signal forces a reset of all internal registers and selects whether the serial or parallel control interface is used. See pin SEN/STB.
43	AVDD1	Supply	Analogue supply (5V).
44	AVDD2	Supply	Analogue supply (5V).
45	AGND5	Supply	Analogue ground (0V).
46	AGND6	Supply	Analogue ground (0V).
47	VRB	Analogue output	Lower reference voltage. This pin must be capacitively decoupled to AGND.
48	VRT	Analogue output	Lower reference voltage. This pin must be capacitively decoupled to AGND.

ABSOLUTE MAXIMUM RATINGS

Absolute Maximum Ratings are stress ratings only. Permanent damage to the device may be caused by continuously operating at or beyond these limits. Device functional operating limits and guaranteed performance specifications are given under Electrical Characteristics at the test conditions specified.



ESD Sensitive Device. This device is manufactured on a CMOS process. It is therefore generically susceptible to damage from excessive static voltages. Proper ESD precautions must be taken during handling and storage of this device.

Wolfson tests its package types according to IPC/JEDEC J-STD-020B for Moisture Sensitivity to determine acceptable storage conditions prior to surface mount assembly. These levels are:

MSL1 = unlimited floor life at <30°C / 85% Relative Humidity. Not normally stored in moisture barrier bag.

MSL2 = out of bag storage for 1 year at <30°C / 60% Relative Humidity. Supplied in moisture barrier bag.

MSL3 = out of bag storage for 168 hours at <30°C / 60% Relative Humidity. Supplied in moisture barrier bag.

The Moisture Sensitivity Level for each package type is specified in Ordering Information.

CONDITION	MIN	MAX
Analogue supply voltages: AVDD1, 2	GND - 0.3V	GND + 7V
Digital supply voltages: DVDD1 – 3	GND - 0.3V	GND + 7V
Digital grounds: DGND1 – 5	GND - 0.3V	GND + 0.3V
Analogue grounds: AGND1 – 6	GND - 0.3V	GND + 0.3V
Digital inputs, digital outputs and digital I/O pins	GND - 0.3V	DVDD2 + 0.3V
Analogue inputs (RINP, GINP, BINP)	GND - 0.3V	AVDD + 0.3V
Other pins	GND - 0.3V	AVDD + 0.3V
Operating temperature range: T _A	0°C	+70°C
Storage temperature	-65°C	+150°C

Notes:

1. GND denotes the voltage of any ground pin.
2. AGND1 – 6 and DGND1 – 5 pins are intended to be operated at the same potential. Differential voltages between these pins will degrade performance.

RECOMMENDED OPERATING CONDITIONS

CONDITION	SYMBOL	MIN	TYP	MAX	UNITS	
Operating temperature range	T _A	0		70	°C	
Analogue supply voltage	AVDD1, 2	4.75	5.0	5.25	V	
Digital core supply voltage	DVDD1	4.75	5.0	5.25	V	
Digital I/O supply voltage	5V I/O	DVDD2, 3	4.75	5.0	5.25	V
	3.3V I/O	DVDD2, 3	2.97	3.3	3.63	V

ELECTRICAL CHARACTERISTICS

Test Conditions

AVDD1 = AVDD2 = DVDD1 = DVDD2 = DVDD3 = 4.75 to 5.25V, AGND = DGND = 0V, T_A = 0 to 70°C, MCLK = 24MHz unless otherwise stated.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Overall System Specification (including 14-bit ADC, PGA, Offset and CDS functions)						
NO MISSING CODES GUARANTEED						
Conversion rate				12		MSPS
Full-scale input voltage range (see Note 1)		Max Gain Min Gain		0.4 4.08		V _{p-p} V _{p-p}
Input signal limits (see Note 2)	V _{IN}		0		AVDD	V
Full-scale transition error		Gain = 0dB; PGA[7:0] = 4B(hex)		20		mV
Zero-scale transition error		Gain = 0dB; PGA[7:0] = 4B(hex)		20		mV
Differential non-linearity	DNL			1.25		LSB
Integral non-linearity	INL			8		LSB
Channel to channel gain matching				1		%
Total output noise		Min Gain Max Gain		1 3		LSB rms LSB rms
References						
Upper reference voltage	VRT			2.85		V
Lower reference voltage	VRB			1.35		V
Input return bias voltage	VRX			1.65		V
Diff. reference voltage (VRT-VRB)	V _{RTB}		1.4	1.5	1.6	V
Output resistance VRT, VRB, VRX				1		Ω
VRLC/Reset-Level Clamp (RLC)						
RLC switching impedance				50		Ω
VRLC short-circuit current				5		mA
VRLC output resistance				2		Ω
VRLC Hi-Z leakage current		VRLC = 0 to AVDD			1	μA
RLCDAC resolution				4		bits
RLCDAC step size, RLCDAC = 0	V _{RLCSTEP}			0.25		V/step
RLCDAC step size, RLCDAC = 1	V _{RLCSTEP}			0.17		V/step
RLCDAC output voltage at code 0(hex), RLCDACRNG = 0	V _{RLCBOT}			0.39		V
RLCDAC output voltage at code 0(hex), RLCDACRNG = 1	V _{RLCBOT}			0.26		V
RLCDAC output voltage at code F(hex) RLCDACRNG, = 0	V _{RLCTOP}			4.16		V
RLCDAC output voltage at code F(hex), RLCDACRNG = 1	V _{RLCTOP}			2.81		V
VRLC deviation			-50		+50	mV
Offset DAC, Monotonicity Guaranteed						
Resolution				8		bits
Differential non-linearity	DNL			0.1	0.5	LSB
Integral non-linearity	INL			0.25	1	LSB
Step size				2.04		mV/step
Output voltage		Code 00(hex) Code FF(hex)		-260 +260		mV mV

Notes:

1. **Full-scale input voltage** denotes the maximum amplitude of the input signal at the specified gain.
2. **Input signal limits** are the limits within which the full-scale input voltage signal must lie.

Test Conditions

AVDD1 = AVDD2 = DVDD1 = DVDD2 = DVDD3 = 4.75 to 5.25V, AGND = DGND = 0V, T_A = 0 to 70°C, MCLK = 24MHz unless otherwise stated.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Programmable Gain Amplifier						
Resolution				8		bits
Gain				$\frac{208}{283 - \text{PGA}[7:0]}$		V/V
Max gain, each channel	G _{MAX}			7.4		V/V
Min gain, each channel	G _{MIN}			0.74		V/V
Gain error, each channel				1		%
Analogue to Digital Converter						
Resolution				14		bits
Speed				12		MSPS
Full-scale input range (2*(VRT-VRB))				3		V
DIGITAL SPECIFICATIONS						
Digital Inputs						
High level input voltage	V _{IH}		0.8 * DVDD2/3			V
Low level input voltage	V _{IL}				0.2 * DVDD2/3	V
High level input current	I _{IH}				1	µA
Low level input current	I _{IL}				1	µA
Input capacitance	C _I			5		pF
Digital Outputs						
High level output voltage	V _{OH}	I _{OH} = 1mA	DVDD2/3 - 0.5			V
Low level output voltage	V _{OL}	I _{OL} = 1mA			0.5	V
High impedance output current	I _{OZ}				1	µA
Digital IO Pins						
Applied high level input voltage	V _{IH}		0.8 * DVDD2/3			V
Applied low level input voltage	V _{IL}				0.2 * DVDD2/3	V
High level output voltage	V _{OH}	I _{OH} = 1mA	DVDD2/3 - 0.5			V
Low level output voltage	V _{OL}	I _{OL} = 1mA			0.5	V
Low level input current	I _{IL}				1	µA
High level input current	I _{IH}				1	µA
Input capacitance	C _I			5		pF
High impedance output current	I _{OZ}				1	µA
Supply Currents						
Total supply current – active (Three channel mode)		MCLK = 24MHz		42	65	mA
Total supply current – active (Single channel mode)		LINEBYLINE = 1 MCLK = 24MHz		35		mA
Total analogue supply current – active (Three channel mode)	I _{AVDD}	MCLK = 24MHz		37		mA
Total analogue supply current – active (One channel mode)	I _{AVDD}	LINEBYLINE = 1 MCLK = 24MHz		30		mA
Digital core supply current, DVDD1 – active (Note1)		MCLK = 24MHz		3		mA
Digital I/O supply current, DVDD2 – active (Note1)		MCLK = 24MHz		2		mA
Supply current – full power down mode				20	60	µA

INPUT VIDEO SAMPLING

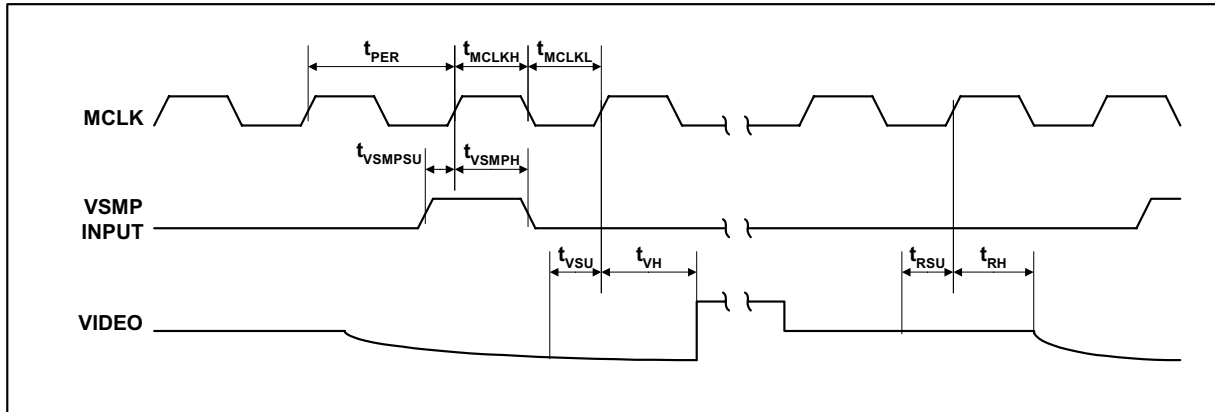


Figure 1 Input Video Timing

Test Conditions

AVDD1 = AVDD2 = DVDD1 = DVDD2 = DVDD3 = 4.75 to 5.25V, AGND = DGND = 0V, T_A = 0 to 70°C, MCLK = 24MHz unless otherwise stated.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
MCLK period	t _{PER}		41.6			ns
MCLK high period	t _{MCLKH}		18.8			ns
MCLK low period	t _{MCLKL}		18.8			ns
VSMP set-up time	t _{VSMPSU}		6			ns
VSMP hold time	t _{VSMPL}		3			ns
Video level set-up time	t _{VSU}		10			ns
Video level hold time	t _{VH}		3			ns
Reset level set-up time	t _{RSU}		10			ns
Reset level hold time	t _{RH}		3			ns

Notes:

1. t_{VSU} and t_{RSU} denote the set-up time required after the input video signal has settled.
2. Parameters are measured at 50% of the rising/falling edge.

OUTPUT DATA TIMING

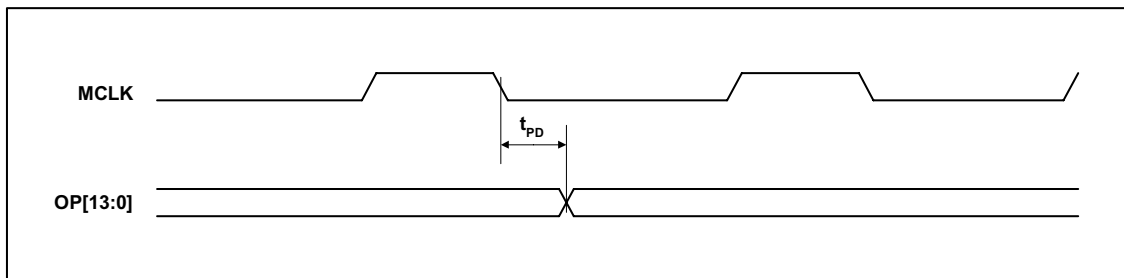


Figure 2 Output Data Timing

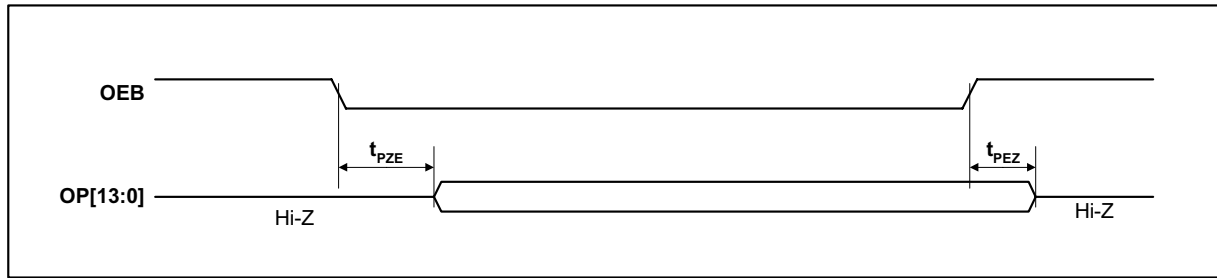


Figure 3 Output Data Enable Timing

Test Conditions

AVDD1 = AVDD2 = DVDD1 = DVDD2 = DVDD3 = 4.75 to 5.25V, AGND = DGND = 0V, T_A = 0 to 70°C, MCLK = 24MHz unless otherwise stated.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Output propagation delay	t _{PD}	I _{OH} = 1mA, I _{OL} = 1mA			40	ns
Output enable time	t _{PZE}				20	ns
Output disable time	t _{PEZ}				15	ns

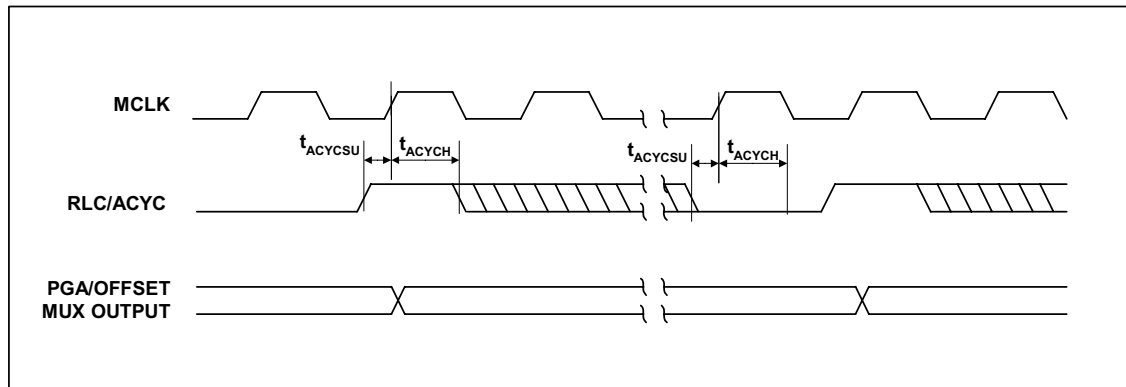


Figure 4 Auto Cycle Timing

Test Conditions

AVDD = DVDD1 = 4.75 to 5.25V, DVDD2 = 2.97 to 3.63V, AGND = DGND = 0V, T_A = 0 to 70°C, MCLK = 32MHz unless otherwise stated.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Auto Cycle set-up time	t _{ACYCSU}		6			ns
Auto Cycle hold time	t _{ACYCH}		3			ns

SERIAL INTERFACE

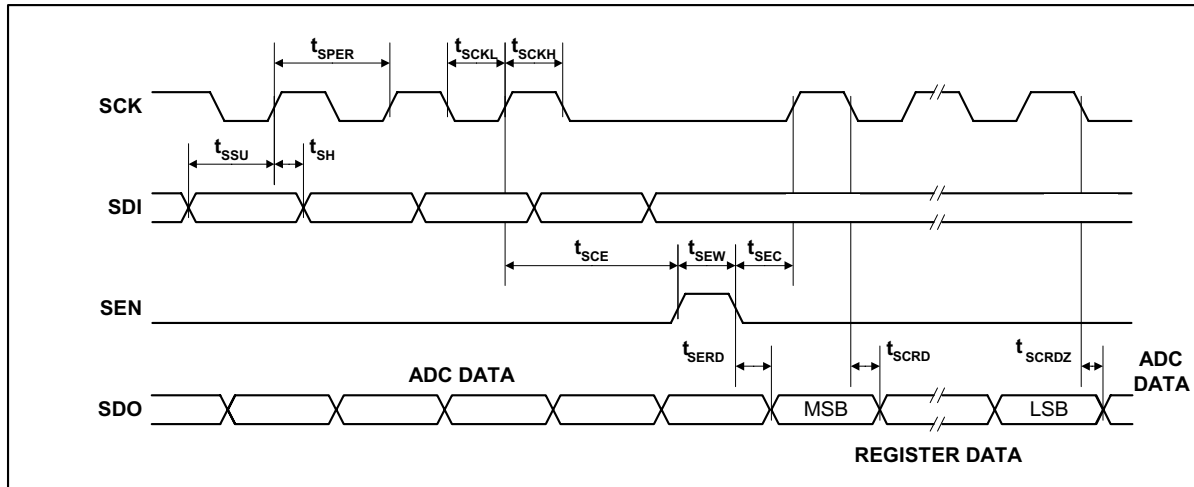


Figure 5 Serial Interface Timing

Test Conditions

AVDD1 = AVDD2 = DVDD1 = DVDD2 = DVDD3 = 4.75 to 5.25V, AGND = DGND = 0V, $T_A = 0$ to 70°C , MCLK = 24MHz unless otherwise stated.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
SCK period	t_{SPER}		41.6			ns
SCK high	t_{SCKH}		18.8			ns
SCK low	t_{SCKL}		18.8			ns
SDI set-up time	t_{SSU}		6			ns
SDI hold time	t_{SH}		6			ns
SCK to SEN set-up time	t_{SCE}		12			ns
SEN to SCK set-up time	t_{SEC}		12			ns
SEN pulse width	t_{SEW}		25			ns
SEN low to SDO = Register data	t_{SERD}				30	ns
SCK low to SDO = Register data	t_{SCRD}				30	ns
SCK low to SDO = ADC data	t_{SCADC}				30	ns

Note: Parameters are measured at 50% of the rising/falling edge.

PARALLEL INTERFACE

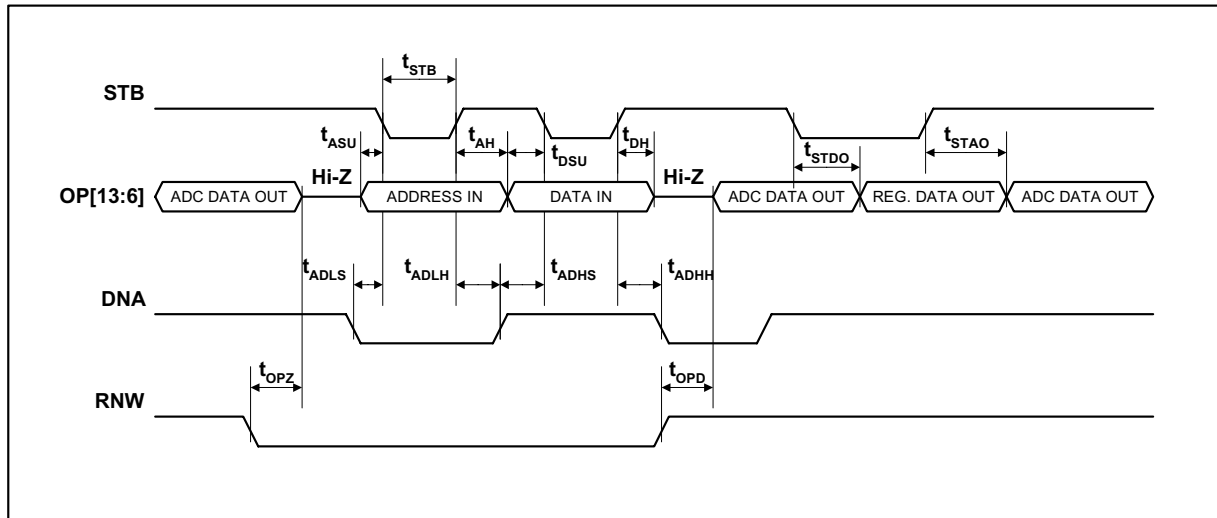


Figure 6 Parallel Interface Timing

Test Conditions

AVDD1 = AVDD2 = DVDD1 = DVDD2 = DVDD3 = 4.75 to 5.25V, AGND = DGND = 0V, T_A = 0 to 70°C, MCLK = 24MHz unless otherwise stated.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
RNW low to OP[13:6] Hi-Z	t_{OPZ}				10	ns
Address set-up time to STB low	t_{ASU}		0			ns
DNA low set-up time to STB low	t_{ADLS}		5			ns
Strobe low time	t_{STB}		30			ns
Address hold time from STB high	t_{AH}		5			ns
DNA low hold time from STB high	t_{ADLH}		5			ns
Data set-up time to STB low	t_{DSU}		0			ns
DNA high set-up time to STB low	t_{ADHS}		5			ns
Data hold time from STB high	t_{DH}		5			ns
Data high hold time from STB high	t_{ADHH}		5			ns
RNW high to OP[13:6] output	t_{OPD}				30	ns
Data output propagation delay from STB low	t_{STDO}				30	ns
ADC data out propagation delay from STB high	t_{STAO}				30	ns

Note: Parameters are measured at 50% of the rising/falling edge.

DEVICE DESCRIPTION

INTRODUCTION

A block diagram of the device showing the signal path is presented on Page 1.

The WM8195 samples up to three inputs (RINP, GINP and BINP) simultaneously. The device then processes the sampled video signal with respect to the video reset level or an internally/externally generated reference level using either one or three processing channels.

Each processing channel consists of an Input Sampling block with optional Reset Level Clamping (RLC) and Correlated Double Sampling (CDS), a 8-bit programmable offset DAC and an 8-bit Programmable Gain Amplifier (PGA).

The ADC then converts each resulting analogue signal to a 14-bit digital word. The digital output from the ADC is presented on a 14-bit wide bus, with optional 8+6-bit, 7+7-bit or 4+4+4+2-bit multiplexed formats.

On-chip control registers determine the configuration of the device, including the offsets and gains applied to each channel. These registers are programmable via a serial or parallel interface.

INPUT SAMPLING

The WM8195 can sample and process one to three inputs through one or three processing channels as follows:

Colour Pixel-by-Pixel: The three inputs (RINP, GINP and BINP) are simultaneously sampled for each pixel and a separate channel processes each input. The signals are then multiplexed into the ADC, which converts all three inputs within the pixel period.

Monochrome: A single chosen input (RINP, GINP, or BINP) is sampled, processed by the corresponding channel, and converted by the ADC. The choice of input and channel can be changed via the control interface, e.g. on a line-by-line basis if required.

Colour Line-by-Line: A single chosen input (RINP, GINP, or BINP) is sampled and multiplexed into the red channel for processing before being converted by the ADC. The input selected can be switched in turn (RINP → GINP → BINP → RINP...) together with the PGA and offset DAC control registers by pulsing the RLC/ACYC pin. This is known as auto-cycling. Alternatively, other sampling sequences can be generated via the control registers. This mode causes the blue and green channels to be powered down. Refer to the Line-by-Line Operation section for more details.

RESET LEVEL CLAMPING (RLC)

To ensure that the signal applied to the WM8195 lies within its input range (0V to AVDD) the CCD output signal is usually level shifted by coupling through a capacitor, C_{IN} . The RLC circuit clamps the WM8195 side of this capacitor to a suitable voltage during the CCD reset period.

A typical input configuration is shown in Figure 7. An internal clamp pulse, CL, is generated from MCLK and VSMP by the Timing Control Block. When CL is active the voltage on the WM8195 side of C_{IN} , at RINP, is forced to the VRFC/VBIAS voltage (V_{VRLC}) by closing of switch 1. When the CL pulse turns off, switch 1 opens, the voltage at RINP initially remains at V_{VRLC} but any subsequent variation in sensor voltage (from reset to video level) will couple through C_{IN} to RINP.

RLC is compatible with both CDS and non-CDS operating modes, as selected by switch 2. Refer to the CDS/Non-CDS Processing section.

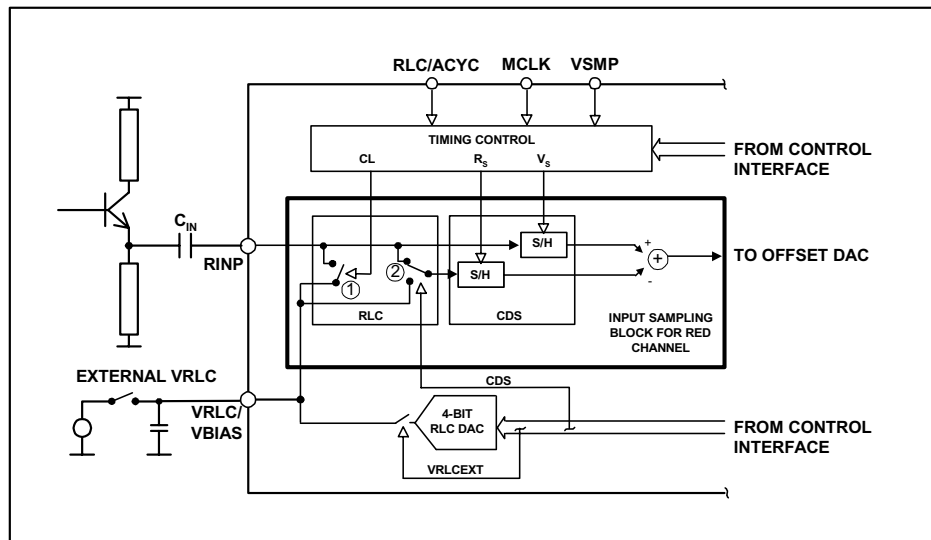


Figure 7 Reset Level Clamping and CDS Circuitry

If auto-cycling is not required, RLC can be selected pixel-by-pixel by pin RLC/ACYC. Figure 8 illustrates control of RLC for a typical CCD waveform, with CL applied during the reset period.

The input signal applied to the RLC/ACYC pin is sampled on the positive edge of MCLK that occurs during each VSMP pulse. The sampled level, high (or low) controls the presence (or absence) of the internal CL pulse on the next reset level. The position of CL can be adjusted by using control bits CDSREF[1:0] (Figure 9).

If auto-cycling is required, pin RLC/ACYC is no longer available for this function and control bit RLCINT determines whether clamping is applied.

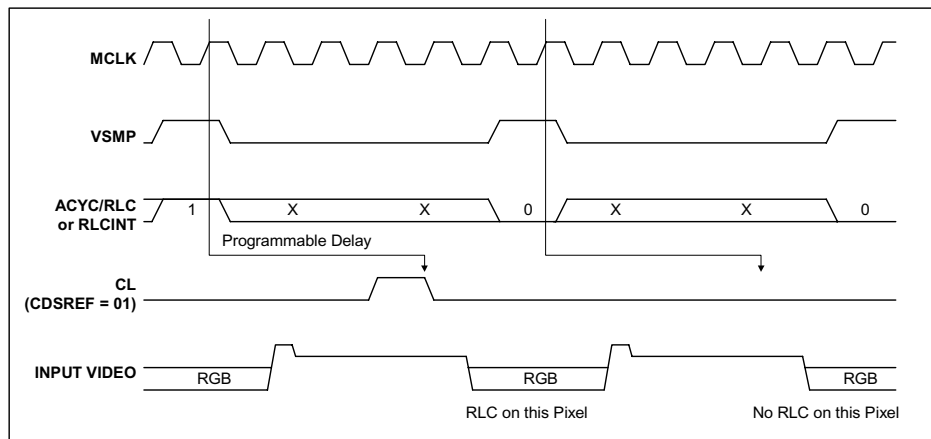


Figure 8 Relationship of RLC Pin, MCLK and VSMP to Internal Clamp Pulse, CL

The VRLC/VBIAS pin can be driven internally by a 4-bit DAC (RLCDAC) by writing to control bits RLCV[3:0]. The RLCDAC range and step size may be increased by writing to control bit RLCDACRNG. Alternatively, the VRLC/VBIAS pin can be driven externally by writing to control bit VRLCEXT to disable the RLCDAC and then applying a d.c. voltage to the pin.

CDS/NON-CDS PROCESSING

For CCD type input signals, the signal may be processed using CDS, which will remove pixel-by-pixel common mode noise. For CDS operation, the video level is processed with respect to the video reset level, regardless of whether RLC has been performed. To sample using CDS, control bit CDS must be set to 1 (default), this sets switch 2 into the position shown in (Figure 7) and causes the signal reference to come from the video reset level. The time at which the reset level is sampled, by clock R_s/CL , is adjustable by programming control bits CDSREF[1:0], as shown in Figure 9.

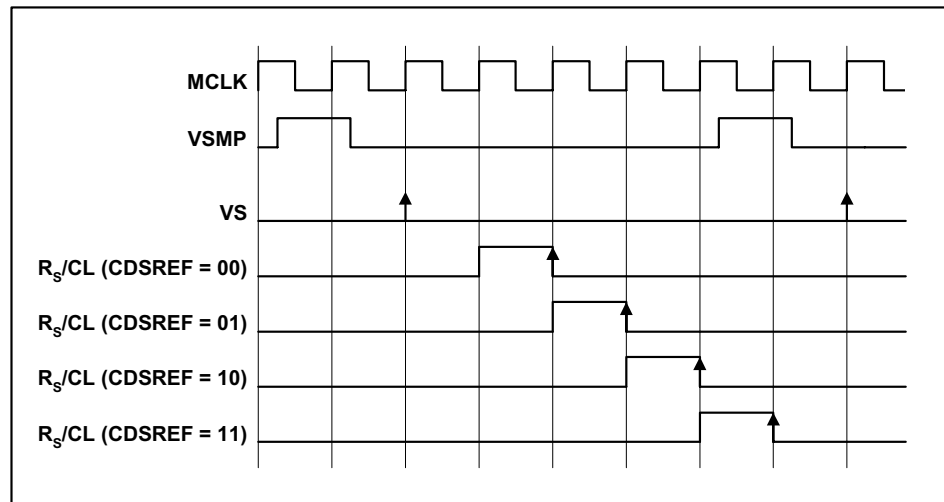


Figure 9 Reset Sample and Clamp Timing

For CIS type sensor signals, non-CDS processing is used. In this case, the video level is processed with respect to the voltage on pin VRLC/VBIAS, generated internally or externally as described above. The VRLC/VBIAS pin is sampled by R_s at the same time as V_s samples the video level in this mode; non-CDS processing is achieved by setting switch 2 in the lower position. CDS = 0.

OFFSET ADJUST AND PROGRAMMABLE GAIN

The output from the CDS block is a differential signal, which is added to the output of an 8-bit Offset DAC to compensate for offsets and then amplified by an 8-bit PGA. The gain and offset for each channel are independently programmable by writing to control bits DAC[7:0] and PGA[7:0].

The gain characteristic of the WM8195 PGA is shown in Figure 10. Figure 11 shows the maximum device input voltage that can be gained up to match the ADC full-scale input range (3V).

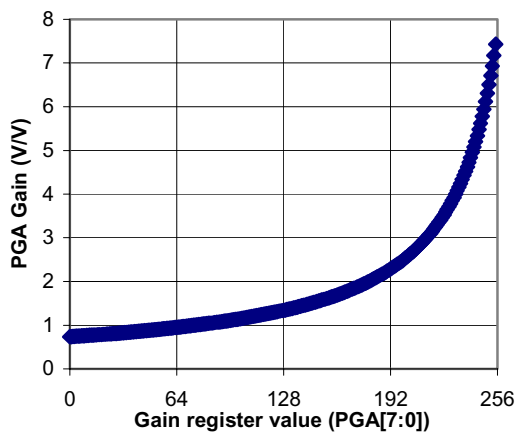


Figure 10 PGA Gain Characteristic

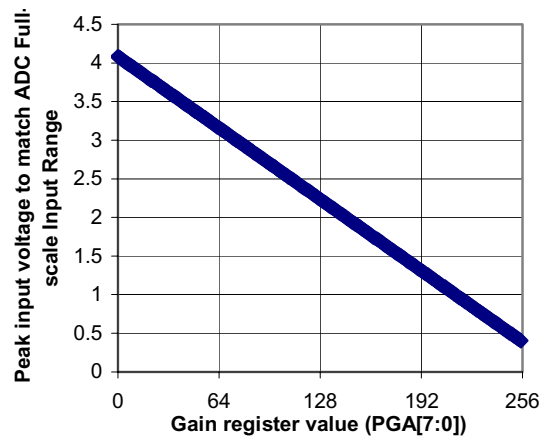


Figure 11 Peak Input Voltage to Match ADC Full-scale Range

In colour line-by-line mode the gain and offset coefficients for each colour can be multiplexed in order (Red → Green → Blue → Red...) by pulsing the ACYC/RLC pin, or controlled via the FME, ACYCNRLC and INTM[1:0] bits. Refer to the Line-by-Line Operation section for more details.

ADC INPUT BLACK LEVEL ADJUST

The output from the PGA should be offset to match the full-scale range of the ADC (3V). For negative-going input video signals, a black level (zero differential) output from the PGA should be offset to the top of the ADC range by setting register bits PGAFS[1:0]=10. For positive going input signal the black level should be offset to the bottom of the ADC range by setting PGAFS[1:0]=11. Bipolar input video is accommodated by setting PGAFS[1:0]=00 or PGAFS[1:0]=01 (zero differential input voltage gives mid-range ADC output).

OVERALL SIGNAL FLOW SUMMARY

Figure 12 represents the processing of the video signal through the WM8195.

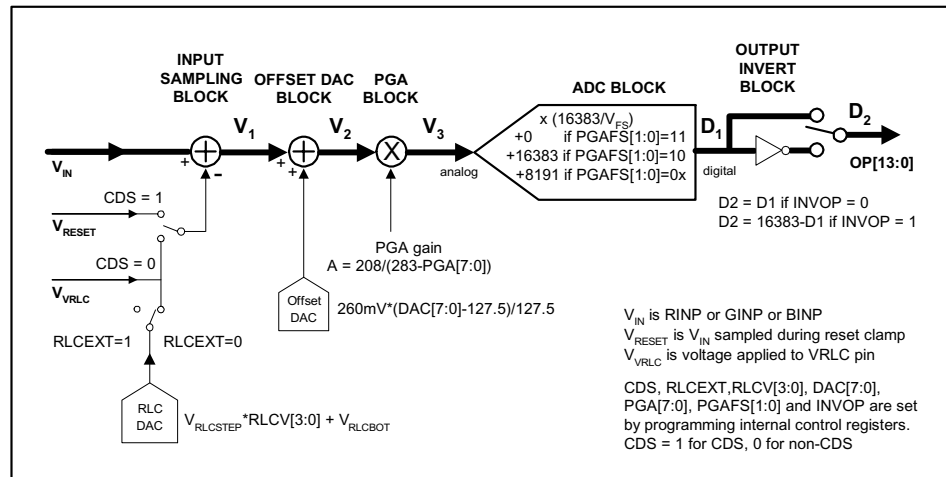


Figure 12 Overall Signal Flow

The **INPUT SAMPLING BLOCK** produces an effective input voltage V_1 . For CDS, this is the difference between the input video level V_{IN} and the input reset level V_{RESET} . For non-CDS this is the difference between the input video level V_{IN} and the voltage on the VRLC/VBIAS pin, V_{VRLC} , optionally set via the RLC DAC.

The **OFFSET DAC BLOCK** then adds the amount of fine offset adjustment required to move the black level of the input signal towards 0V, producing V_2 .

The **PGA BLOCK** then amplifies the white level of the input signal to maximise the ADC range, outputting voltage V_3 .

The **ADC BLOCK** then converts the analogue signal, V_3 , to a 14-bit unsigned digital output, D_1 .

The digital output is then inverted, if required, through the **OUTPUT INVERT BLOCK** to produce D_2 .

CALCULATING OUTPUT FOR ANY GIVEN INPUT

The following equations describe the processing of the video and reset level signals through the WM8199. The values of V_1 , V_2 and V_3 are often calculated in reverse order during device setup. The PGA value is written first to set the input Voltage range, the Offset DAC is then adjusted to compensate for any Black/Reset level offsets and finally the RLC DAC value is set to position the reset level correctly during operation.

Note: Refer to WAN0123 for detailed information on device calibration procedures.

The following equations describe the processing of the video and reset level signals through the WM8195.

INPUT SAMPLING BLOCK: INPUT SAMPLING AND REFERENCING

If CDS = 1, (CDS operation) the previously sampled reset level, V_{RESET} , is subtracted from the input video.

$$V_1 = V_{\text{IN}} - V_{\text{RESET}} \dots\dots\dots \text{Eqn. 1}$$

If CDS = 0, (non-CDS operation) the simultaneously sampled voltage on pin VRLC is subtracted instead.

$$V_1 = V_{\text{IN}} - V_{\text{VRLC}} \dots\dots\dots \text{Eqn. 2}$$

If RLCEXT = 1, V_{VRLC} is an externally applied voltage on pin VRLC/VBIAS.

If RLCEXT = 0, V_{VRLC} is the output from the internal RLC DAC.

$$V_{\text{VRLC}} = (V_{\text{RLCSTEP}} * \text{RLCV}[3:0]) + V_{\text{RLCBOT}} \dots\dots\dots \text{Eqn. 3}$$

V_{RLCSTEP} is the step size of the RLC DAC and V_{RLCBOT} is the minimum output of the RLC DAC.

OFFSET DAC BLOCK: OFFSET (BLACK-LEVEL) ADJUST

The resultant signal V_1 is added to the offset DAC output.

$$V_2 = V_1 + \{260\text{mV} * (\text{DAC}[7:0] - 127.5)\} / 127.5 \dots\dots\dots \text{Eqn. 4}$$

PGA NODE: GAIN ADJUST

The signal is then multiplied by the PGA gain,

$$V_3 = V_2 * 208 / (283 - \text{PGA}[7:0]) \dots\dots\dots \text{Eqn. 5}$$

ADC BLOCK: ANALOGUE-DIGITAL CONVERSION

The analogue signal is then converted to a 14-bit unsigned number, with input range configured by PGAFS[1:0].

$$D_1[13:0] = \text{INT}\{ (V_3 / V_{\text{FS}}) * 16383\} + 8191 \quad \text{PGAFS}[1:0] = 00 \text{ or } 01 \dots\dots \text{Eqn. 6}$$

$$D_1[13:0] = \text{INT}\{ (V_3 / V_{\text{FS}}) * 16383\} \quad \text{PGAFS}[1:0] = 11 \dots\dots\dots \text{Eqn. 7}$$

$$D_1[13:0] = \text{INT}\{ (V_3 / V_{\text{FS}}) * 16383\} + 16383 \quad \text{PGAFS}[1:0] = 10 \dots\dots\dots \text{Eqn. 8}$$

where the ADC full-scale range, $V_{\text{FS}} = 3\text{V}$.

OUTPUT INVERT BLOCK: POLARITY ADJUST

The polarity of the digital output may be inverted by control bit INVOP.

$$D_2[13:0] = D_1[13:0] \quad (\text{INVOP} = 0) \dots\dots\dots \text{Eqn. 9}$$

$$D_2[13:0] = 16383 - D_1[13:0] \quad (\text{INVOP} = 1) \dots\dots\dots \text{Eqn. 10}$$

OUTPUT FORMATS

The digital data output from the ADC is available to the user in either 14-bit parallel or 8/7/4-bit wide multiplexed formats by setting control bits MUXOP[1:0]. Latency of valid output data with respect to VSMP is programmable by writing to control bits DEL[1:0]. The latency for each mode is shown in the Operating Mode Timing Diagrams section.

Figure 13 shows the output data formats for Modes 1 – 2 and 4 – 6. Figure 14 shows the output data formats for Mode 3. Table 1 summarises the output data obtained for each format.

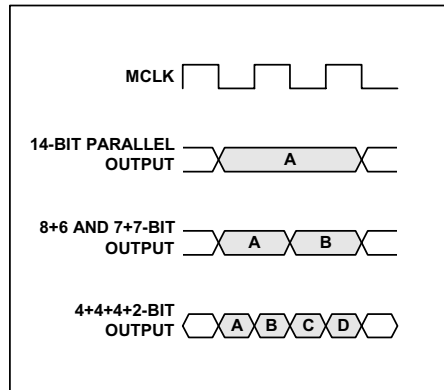


Figure 13 Output Data Formats (Modes 1 – 2, 4 – 6)

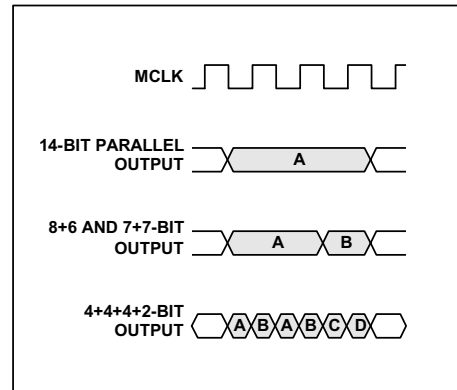


Figure 14 Output Data Formats (Mode 3)

OUTPUT FORMAT	MUXOP[1:0]	OUTPUT PINS	OUTPUT
14-bit parallel	00	OP[13:0]	A = d13, d12, d11, d10, d9, d8, d7, d6, d5, d4, d3, d2, d1, d0
8+6-bit multiplexed	01	OP[13:6]	A = d13, d12, d11, d10, d9, d8, d7, d6 B = d5, d4, d3, d2, d1, d0, CC, OVRNG
7+7-bit	10	OP[13:6]	A = d13, d12, d11, d10, d9, d8, d7, CC B = d6, d5, d4, d3, d2, d1, d0, OVRNG
4+4+4+2-bit (nibble)	11	OP[13:10]	A = d13, d12, d11, d10 B = d9, d8, d7, d6 C = d5, d4, d3, d2 D = d1, d0, CC, OVRNG

Table 1 Details of Output Data Shown in Figure 13 and Figure 14.

FLAGS

The following flags are output during multiplexed modes:

CC can be used in colour modes 1 and 5 to identify the green channel output, from which the blue and red data can be identified.

INPUT	CC
RINP	0
GINP	1
BINP	0

Table 2 Input Sampled Flags CC[1:0]

OVRNG indicates that the current output data was produced by an input signal that exceeded the input range limit of the device. 1 = out of range, 0 = within range.

CONTROL INTERFACE

The internal control registers are programmable via the serial or parallel digital control interface. The register contents can be read back via the parallel interface on pins OP[13:6], or via the serial interface on pin OP[13]/SDO.

Note: It is recommended that a software reset is carried out after the power-up sequence, before writing to any other register. This ensures that all registers are set to their default values (as shown in Table 6).

SERIAL INTERFACE: REGISTER WRITE

Figure 15 shows register writing in serial mode. Three pins, SCK, SDI and SEN are used. A six-bit address (a5, 0, a3, a2, a1, a0) is clocked in through SDI, MSB first, followed by an eight-bit data word (b7, b6, b5, b4, b3, b2, b1, b0), also MSB first. Each bit is latched on the rising edge of SCK. When the data has been shifted into the device, a pulse is applied to SEN to transfer the data to the appropriate internal register. Note all valid registers have address bit a4 equal to 0 in write mode.

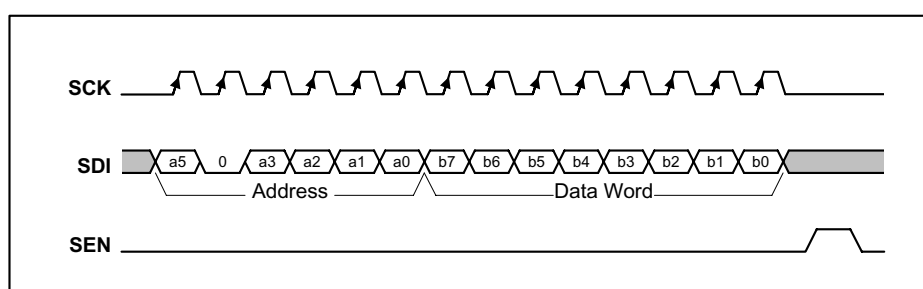


Figure 15 Serial Interface Register Write

Using the serial interface, a software reset is carried out by writing to Address “000100” with any value of data (i.e. Data Word = XXXXXXXX).

SERIAL INTERFACE: REGISTER READ-BACK

Figure 16 shows register read-back in serial mode. Read-back is initiated by writing to the serial bus as described above but with address bit a4 set to 1, followed by an 8-bit dummy data word. Writing address (a5, 1, a3, a2, a1, a0) will cause the contents (d7, d6, d5, d4, d3, d2, d1, d0) of corresponding register (a5, 0, a3, a2, a1, a0) to be output MSB first on pin SDO (on the falling edge of SCK). Note that pin SDO is shared with an output pin, OP[13], therefore OEB should always be held low when register read-back data is expected on this pin. The next word may be read in to SDI while the previous word is still being output on SDO.

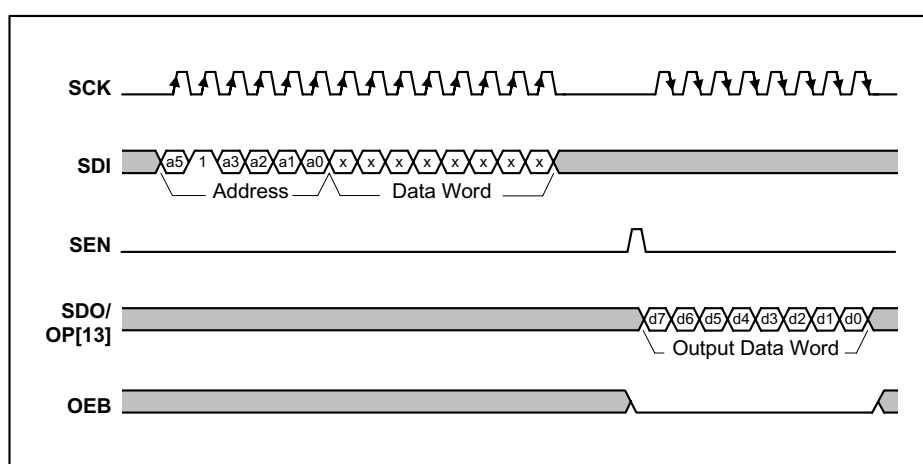


Figure 16 Serial Interface Register Read-back

PARALLEL INTERFACE: REGISTER WRITE

Figure 17 shows register write in parallel mode. The parallel interface uses bits OP[13:6] of the output bus and the STB, DNA and RNW pins. Pin RNW must be low during a write operation. The DNA pin defines whether the data byte is address (low) or data (high). The 6-bit address (a5, 0, a3, a2, a1, a0) is input into OP[11:6], LSB into OP[6], (OP[12] and OP[13] are ignored) when DNA is low, then the 8-bit data word is input into OP[13:6], LSB into OP[6], when DNA is high. The data bus OP[13:6] for both address and data is clocked in on the falling edge of STB. Note all valid registers have address bit a4 equal to 0.

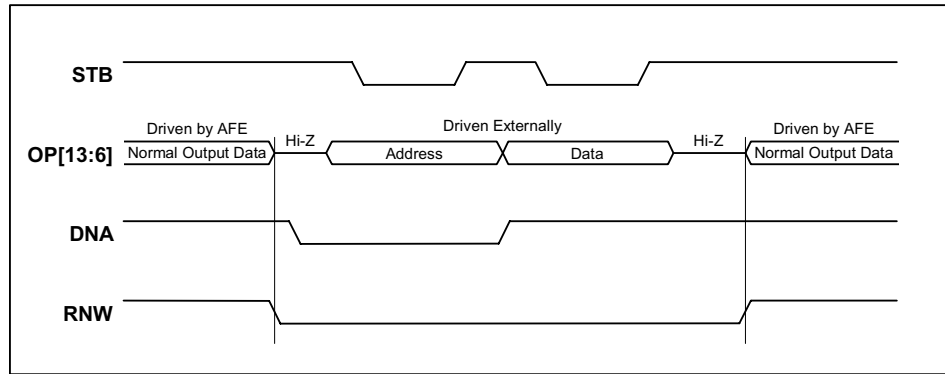


Figure 17 Parallel Interface Register Write

Using the parallel interface, a software reset is carried out by writing “000100” to OP[13:8] when RNW and DNA are low. Any value of data can be written for this address when DNA changes to high (i.e. Data = XXXXXXXX on OP[15:8]).

PARALLEL INTERFACE: REGISTER READ-BACK

Figure 18 shows register read-back in parallel mode. Read-back is initiated by writing the 6-bit address (a5, 1, a3, a2, a1, a0) into OP[11:6] by pulsing the STB pin low. Note that a4 = 1 and pins RNW and DNA are low. When RNW and DNA are high and STB is strobed again, the contents (d7, d6, d5, d4, d3, d2, d1, d0) of the corresponding register (a5, 0, a3, a2, a1, a0) will be output on OP[13:6], LSB on pin OP[6]. Until STB is pulsed low, the current contents of the ADC (shown as Normal Output Data) will be present on OP[13:6]. Note that the register data becomes available on the output data pins so OEB should be held low when read-back data is expected.

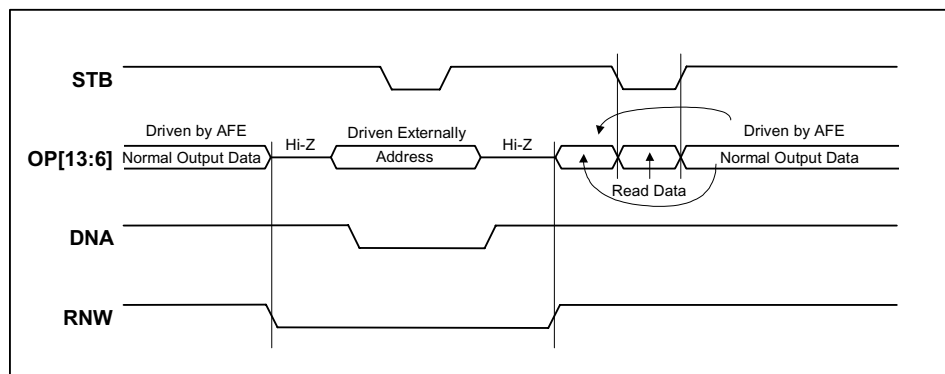


Figure 18 Parallel Interface Register Read-back

TIMING REQUIREMENTS

To use this device a master clock (MCLK) of up to 24MHz and a per-pixel synchronisation clock (VSMP) of up to 12MHz are required. These clocks drive a timing control block, which produces internal signals to control the sampling of the video signal. MCLK to VSMP ratios and maximum sample rates for the various modes are shown in Table 5.

PROGRAMMABLE VSMP DETECT CIRCUIT

The VSMP input is used to determine the sampling point and frequency of the WM8195. Under normal operation a pulse of 1 MCLK period should be applied to VSMP at the desired sampling frequency (as shown in the Operating Mode Timing Diagrams) and the input sample will be taken on the first rising MCLK edge after VSMP has gone low. However, in certain applications such a signal may not be readily available. The programmable VSMP detect circuit in the WM8195 allows the sampling point to be derived from any signal of the correct frequency, such as a CCD shift register clock, when applied to the VSMP pin.

When enabled, by setting the VSMPDET control bit, the circuit detects either a rising or falling edge (determined by POSNNEG control bit) on the VSMP input pin and generates an internal VSMP pulse. This pulse can optionally be delayed by a number of MCLK periods, specified by the VDEL[2:0] bits. Figure 19 shows the internal VSMP pulses that can be generated by this circuit for a typical clock input signal. The internal VSMP pulse is then applied to the timing control block in place of the normal VSMP pulse provided from the input pin. The sampling point then occurs on the first rising MCLK edge after this internal VSMP pulse, as shown in the Operating Mode Timing Diagrams.

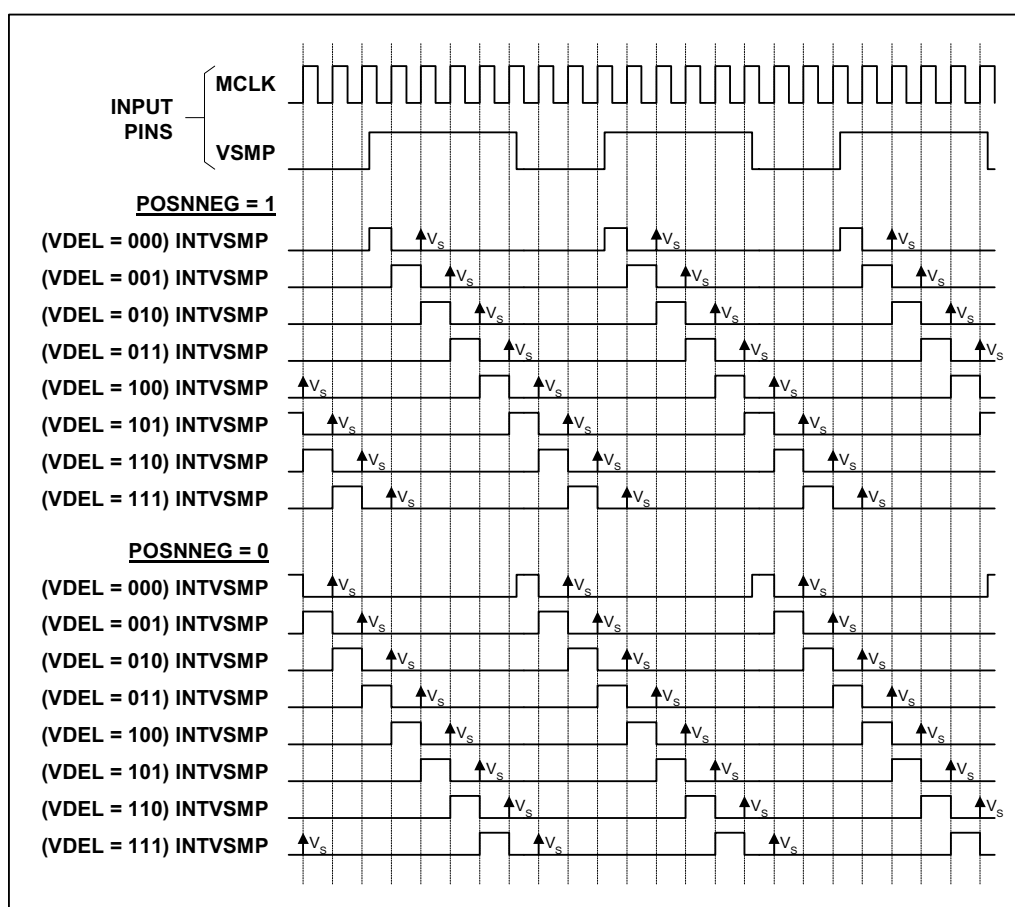


Figure 19 Internal VSMP Pulses Generated by Programmable VSMP Detect Circuit

REFERENCES

The ADC reference voltages are derived from an internal bandgap reference, and buffered to pins VRT and VRB, where they must be decoupled to ground. Pin VRX is driven by a similar buffer, and also requires decoupling. The output buffer from the RLCDAC also requires decoupling at pin VRLC/VBIAS.

POWER SUPPLY

The WM8195 can run from a 5V single supply or from split 5V (core) and 3.3V (digital interface) supplies.

POWER MANAGEMENT

Power management for the device is performed via the Control Interface. The device can be powered on or off completely by setting the EN bit and SELPD bit low. Alternatively, when control bit SELPD is high, only blocks selected by further control bits (SELDIS[3:0]) are powered down. This allows the user to optimise power dissipation in certain modes, or to define an intermediate standby mode to allow a quicker recovery into a fully active state. In Line-by-Line operation, the green and blue channel PGAs are automatically powered down.

All the internal registers maintain their previously programmed value in power down modes and the control interface inputs remain active. Table 3 summarises the power down control bit functions.

EN	SELPD	
0	0	Device completely powers down.
1	0	Device completely powers up.
X	1	Blocks with respective SELDIS[3:0] bit high are disabled.

Table 3 Power Down Control

LINE-BY-LINE OPERATION

Certain linear sensors (e.g. Contact Image Sensors) give colour output on a line-by-line basis. i.e. a full line of red pixels followed by a line of green pixels followed by a line of blue pixels. In order to accommodate this type of signal the WM8195 can be set into Monochrome mode, with the input channel switched by writing to control bits CHAN[1:0] between every line. Alternatively, the WM8195 can be placed into colour line-by-line mode by setting the LINEBYLINE control bit. When this bit is set the green and blue processing channels are powered down and the device is forced internally to only operate in MONO mode (because only one colour is sampled at a time) through the red channel. Figure 20 shows the signal path when operating in colour line-by-line mode.

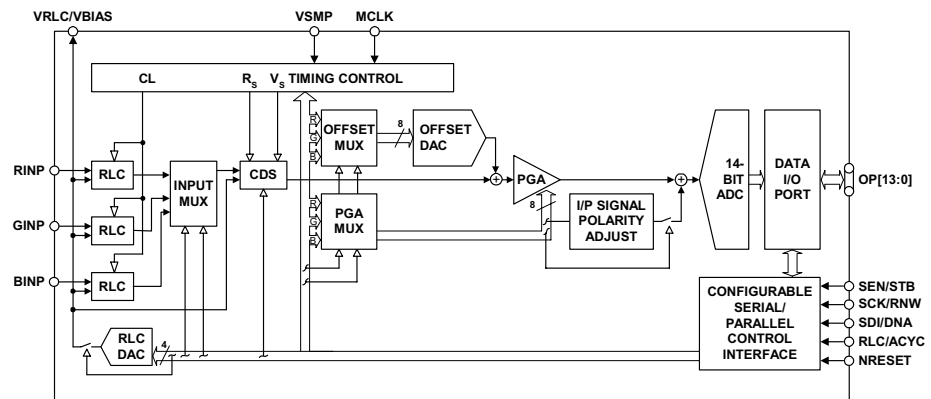


Figure 20 Signal Path When in Line-by-Line Mode

In this mode the input multiplexer and (optionally) the PGA/Offset register multiplexers can be auto-cycled by the application of pulses to the RLC/ACYC input pin by setting the ACYCNRLC register bit. See Figure 4 for detailed timing information. The multiplexers change on the first MCLK rising edge after RLC/ACYC is taken high. A write to the auto-cycle reset register causes these multiplexers to be reset; selecting the RINP pin and the RED offset/gain registers. Alternatively, all three multiplexers can be controlled via the serial interface by writing to register bits INTM[1:0] to select the desired colour. It is also possible for the input multiplexer to be controlled separately from the PGA and Offset multiplexers. Table 4 describes all the multiplexer selection modes that are possible.

FME	ACYNRLC	NAME	DESCRIPTION
0	0	Internal, no force mux	Input mux, offset and gain registers determined by internal register bits INTM1, INTM0.
0	1	Auto-cycling, no force mux	Input mux, offset and gain registers auto-cycled, RINP → GINP → BINP → RINP... on RLC/ACYC pulse.
1	0	Internal, force mux	Input mux selected from internal register bits FM1, FM0; Offset and gain registers selected from internal register bits INTM1, INTM0.
1	1	Auto-cycling, force mux	Input mux selected from internal register bits FM1, FM0; Offset and gain registers auto-cycled, RED → GREEN → BLUE → RED... on RLC/ACYC pulse.

Table 4 Colour Selection Description in Line-by-Line Mode

OPERATING MODES

Table 5 summarises the most commonly used modes, the clock waveforms required and the register contents required for CDS and non-CDS operation.

MODE	DESCRIPTION	CDS AVAILABLE	MAX SAMPLE RATE	SENSOR INTERFACE DESCRIPTION	TIMING REQUIREMENTS	REGISTER CONTENTS WITH CDS	REGISTER CONTENTS WITHOUT CDS
1	Colour Pixel-by-Pixel	Yes	4MSPS x 3 chans	The 3 input channels are sampled in parallel. The signal is then gain and offset adjusted before being multiplexed into a single data stream and converted by the ADC, giving an output data rate of 12MSPS max.	MCLK max = 24MHz MCLK: VSMP ratio is 6:1	SetReg1: 03(hex)	SetReg1: 01(hex)
2	Monochrome/ Colour Line-by-Line	Yes	4MSPS x 1 chan	As mode 1 except: Only one input channel at a time is continuously sampled.	MCLK max = 24MHz MCLK: VSMP ratio is 6:1	SetReg1: 07(hex)	SetReg1: 05(hex)
3	Fast Monochrome/ Colour Line-by-Line	Yes	8MSPS x 1 chan	Identical to mode 2	MCLK max = 24MHz MCLK: VSMP ratio is 3:1	Identical to mode 2 plus SetReg3: bits 5:4 must be set to 0(hex)	Identical to mode 2
4	Maximum speed Monochrome/ Colour Line-by-Line	No	12MSPS x 1 chan	Identical to mode 2	MCLK max = 24MHz MCLK: VSMP ratio is 2:1	CDS not possible	SetReg1: 45(hex)
5	Slow Colour Pixel-by-Pixel	Yes	3MSPS x 3 chans	Identical to mode 1	MCLK max = 24MHz MCLK: VSMP ratio is 2n:1, n ≥ 4	Identical to mode 1	Identical to mode 1
6	Slow Monochrome/ Colour Line-by-Line	Yes	3MSPS x 1 chan	Identical to mode 2	MCLK max = 24MHz MCLK: VSMP ratio is 2n:1, n ≥ 4	Identical to mode 2	Identical to mode 2

Table 5 WM8195 Operating Modes

Notes:

1. In Monochrome mode, Setup Register 3 bits 7:6 determine which input is to be sampled.
2. For Colour Line-by-Line, set control bit LINEBYLINE. For input selection, refer to Table 4, Colour Selection Description in Line-by-Line Mode.

OPERATING MODE TIMING DIAGRAMS

The following diagrams show 14-bit parallel format output and MCLK, VSMP and input video requirements for operation of the most commonly used modes as shown in Table 5. The diagrams are identical for both CDS and non-CDS operation. Outputs from RINP, GINP and BINP are shown as R, G and B respectively. X denotes invalid data.

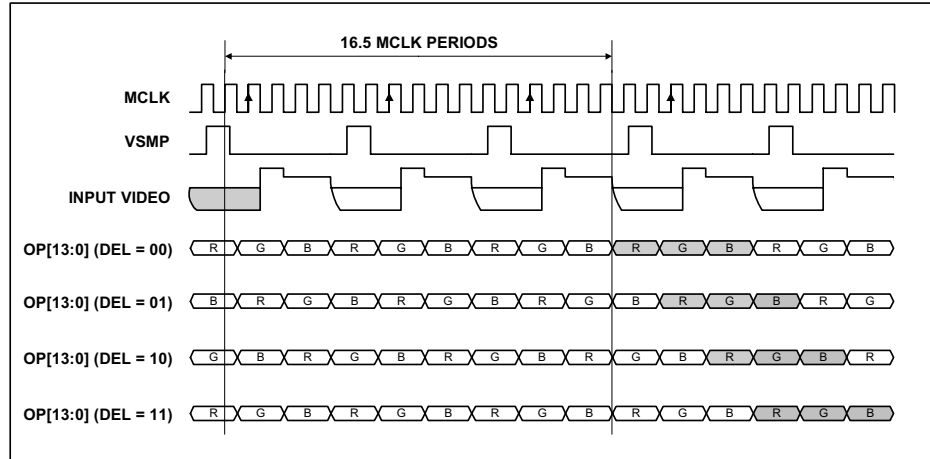


Figure 21 Mode 1 Operation

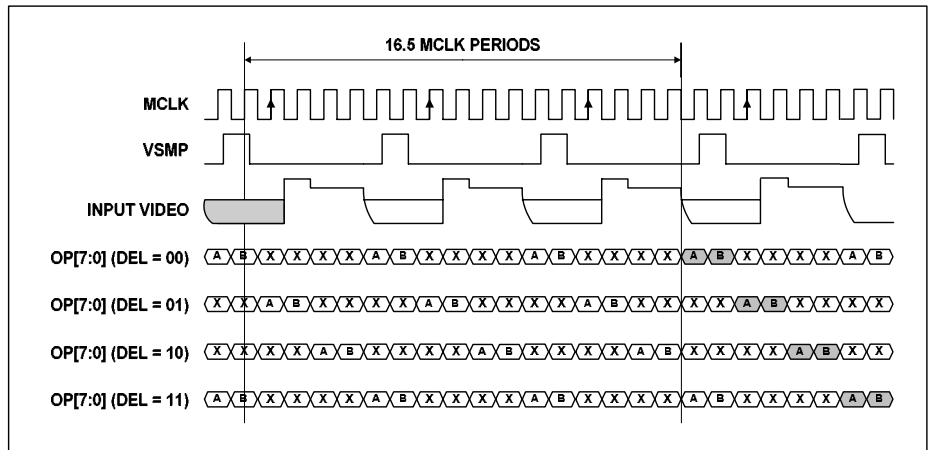


Figure 22 Mode 2 Operation

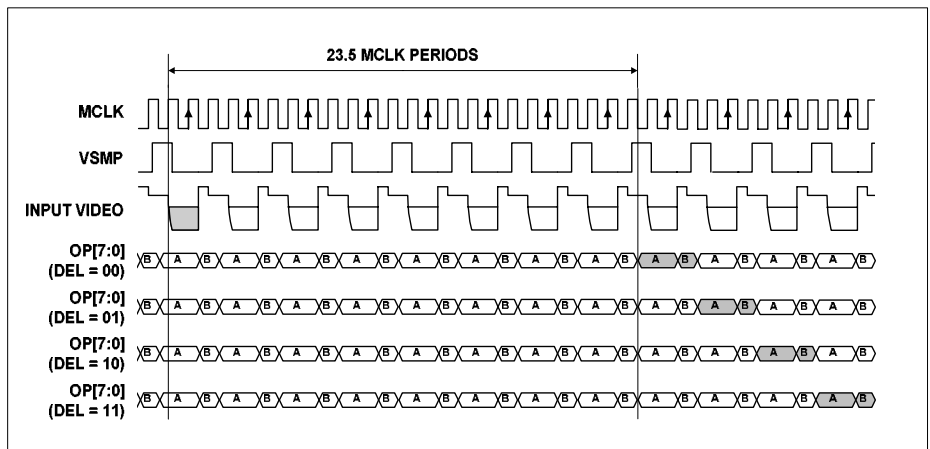


Figure 23 Mode 3 Operation

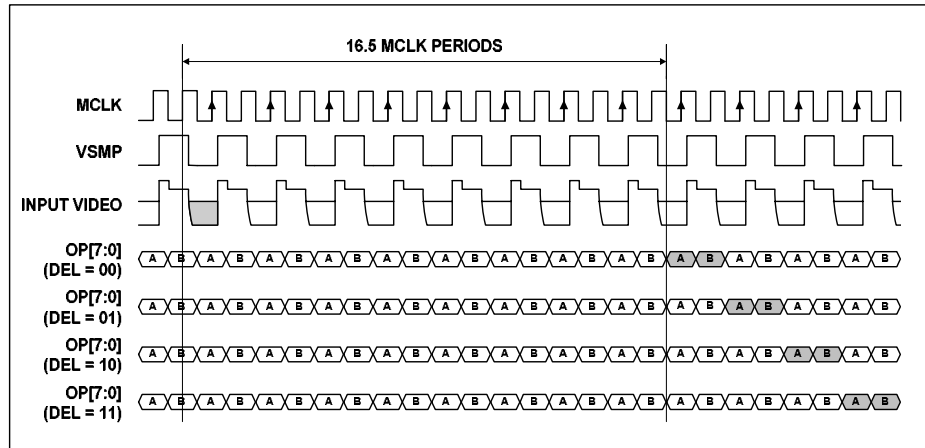


Figure 24 Mode 4 Operation

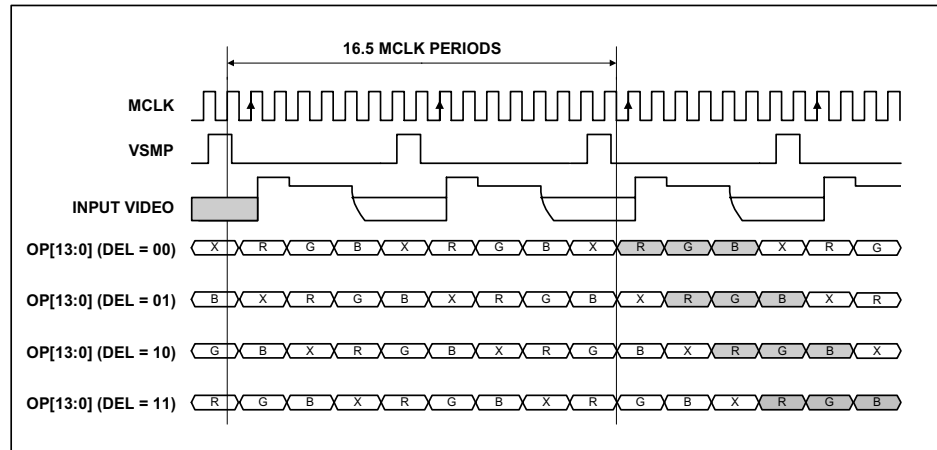


Figure 25 Mode 5 Operation (MCLK:VSMP Ratio = 8:1)

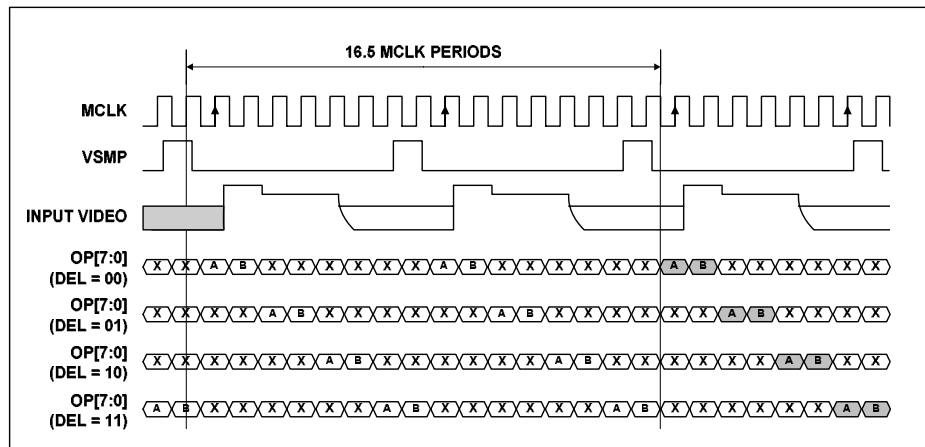


Figure 26 Mode 6 Operation (MCLK:VSMP Ratio = 8:1)

DEVICE CONFIGURATION

REGISTER MAP

The following table describes the location of each control bit used to determine the operation of the WM8195. The register map is programmed by writing the required codes to the appropriate addresses via the serial or parallel interface.

ADDRESS <a5:a0>	DESCRIPTION	DEF (hex)	RW	BIT							
				b7	b6	b5	b4	b3	b2	b1	b0
000001	Setup Reg 1	03	RW		MODE4	PGAFS[1]	PGAFS[0]	SELPD	MONO	CDS	EN
000010	Setup Reg 2	20	RW	DEL[1]	DEL[0]	RLCDACRNG	0	VRLCEXT	INVOP	MUXOP[1]	MUXOP[0]
000011	Setup Reg 3	1F	RW	CHAN[1]	CHAN[0]	CDSREF [1]	CDSREF [0]	RLCV[3]	RLCV[2]	RLCV[1]	RLCV[0]
000100	Software Reset	00	W								
000101	Auto-cycle Reset	00	W								
000110	Setup Reg 4	00	RW	FM[1]	FM[0]	INTM[1]	INTM[0]	RLCINT	FME	ACYCNRLC	LINEBYLINE
000111	Revision Number	41	R								
001000	Setup Reg 5	00	RW	0	0	0	POSNNEG	VDEL[2]	VDEL[1]	VDEL[0]	VSMPDET
001001	Setup Reg 6	00	RW	0	0	0	0	SELDIS[3]	SELDIS[2]	SELDIS[1]	SELDIS[0]
001010	Reserved	00	RW	0	0	0	0	0	0	0	0
001011	Reserved	00	RW	0	0	0	0	0	0	0	0
001100	Reserved	00	RW	0	0	0	0	0	0	0	0
100000	DAC Value (Red)	80	RW	DAC[7]	DAC[6]	DAC[5]	DAC[4]	DAC[3]	DAC[2]	DAC[1]	DAC[0]
100001	DAC Value (Green)	80	RW	DAC[7]	DAC[6]	DAC[5]	DAC[4]	DAC[3]	DAC[2]	DAC[1]	DAC[0]
100010	DAC Value (Blue)	80	RW	DAC[7]	DAC[6]	DAC[5]	DAC[4]	DAC[3]	DAC[2]	DAC[1]	DAC[0]
100011	DAC Value (RGB)	80	W	DAC[7]	DAC[6]	DAC[5]	DAC[4]	DAC[3]	DAC[2]	DAC[1]	DAC[0]
101000	PGA Gain (Red)	00	RW	PGA[7]	PGA[6]	PGA[5]	PGA[4]	PGA[3]	PGA[2]	PGA[1]	PGA[0]
101001	PGA Gain (Green)	00	RW	PGA[7]	PGA[6]	PGA[5]	PGA[4]	PGA[3]	PGA[2]	PGA[1]	PGA[0]
101010	PGA Gain (Blue)	00	RW	PGA[7]	PGA[6]	PGA[5]	PGA[4]	PGA[3]	PGA[2]	PGA[1]	PGA[0]
101011	PGA Gain (RGB)	00	W	PGA[7]	PGA[6]	PGA[5]	PGA[4]	PGA[3]	PGA[2]	PGA[1]	PGA[0]

Table 6 Register Map

REGISTER	BIT NO	BIT NAME(S)	DEFAULT	DESCRIPTION
Setup Register 4	0	LINEBYLINE	0	Selects line by line operation 0 = normal operation, 1 = line by line operation. When line by line operation is selected MONO is forced to 1 and CHAN[1:0] to 00 internally, ensuring that the correct internal timing signals are produced. Green and Blue PGAs are also disabled to save power.
	1	ACYCNRLC	0	When LINEBYLINE = 0 this bit has no effect. When LINEBYLINE = 1 this bit determines the function of the RLC/ACYC input pin and the input multiplexer and offset/gain register controls. 0 = RLC/ACYC pin enabled for Reset Level Clamp. Internal selection of input and gain/offset multiplexers, 1 = Auto-cycling enabled by pulsing the RLC/ACYC input pin. See Table 4, Colour Selection Description in Line-by-Line Mode for colour selection mode details. When auto-cycling is enabled, the RLC/ACYC pin cannot be used for reset level clamping. The RLCINT bit may be used instead.
	2	FME	0	When LINEBYLINE = 0 this bit has no effect. When LINEBYLINE = 1 this bit controls the input force mux mode: 0 = No force mux, 1 = Force mux mode. Forces the input mux to be selected by FM[1:0] separately from gain and offset multiplexers. See Table 4 for details.
	3	RLCINT	0	When LINEBYLINE = 1 and ACYCNRLC = 1 this bit is used to determine whether Reset Level Clamping is used. 0 = RLC disabled, 1 = RLC enabled.
	5:4	INTM[1:0]	00	Colour selection bits used in internal modes. 00 = Red, 01 = Green, 10 = Blue and 11 = Reserved. See Table 4 for details.
	7:6	FM[1:0]	00	Colour selection bits used in input force mux modes. 00 = RINP, 01 = GINP, 10 = BINP and 11 = Reserved. See Table 4 for details.
Setup Register 5	0	VSMPDET	0	0 = Normal operation, signal on VSMP input pin is applied directly to Timing Control block. 1 = Programmable VSMP detect circuit is enabled. An internal synchronisation pulse is generated from signal applied to VSMP input pin and is applied to Timing Control block.
	3:1	VDEL[2:0]	000	When VSMPDET = 0 these bits have no effect. When VSMPDET = 1 these bits set a programmable delay from the detected edge of the signal applied to the VSMP pin. The internally generated pulse is delayed by VDEL MCLK periods from the detected edge. See Figure 19, Internal VSMP Pulses Generated for details.
	4	POSNEG	0	When VSMPDET = 0 this bit has no effect. When VSMPDET = 1 this bit controls whether positive or negative edges are detected: 0 = Negative edge on VSMP pin is detected and used to generate internal timing pulse. 1 = Positive edge on VSMP pin is detected and used to generate internal timing pulse. See Figure 19 for further details.
Setup Register 6	3:0	SELDIS[3:0]	0000	Selective power disable register - activated when SELPD = 1. Each bit disables respective cell when 1, enabled when 0. SELDIS[0] = Red CDS, PGA SELDIS[1] = Green CDS, PGA SELDIS[2] = Blue CDS, PGA SELDIS[3] = ADC

REGISTER	BIT NO	BIT NAME(S)	DEFAULT	DESCRIPTION
Offset DAC (Red)	7:0	DAC[7:0]	0	Red channel offset DAC value.
Offset DAC (Green)	7:0	DAC[7:0]	0	Green channel offset DAC value
Offset DAC (Blue)	7:0	DAC[7:0]	0	Blue channel offset DAC value
Offset DAC (RGB)	7:0	DAC[7:0]	0	A write to this register location causes the red, green and blue offset DAC registers to be overwritten by the new value
PGA gain (Red)	7:0	PGA[7:0]	0	Determines the gain of the red channel PGA according to the equation: Red channel PGA gain = $208/(283-PGA[7:0])$
PGA gain (Green)	7:0	PGA[7:0]	0	Determines the gain of the green channel PGA according to the equation: Green channel PGA gain = $208/(283-PGA[7:0])$
PGA gain (Blue)	7:0	PGA[7:0]	0	Determines the gain of the blue channel PGA according to the equation: Blue channel PGA gain = $208/(283-PGA[7:0])$
PGA gain (RGB)	7:0	PGA[7:0]	0	A write to this register location causes the red, green and blue PGA gain registers to be overwritten by the new value

Table 7 Register Control Bits

RECOMMENDED EXTERNAL COMPONENTS

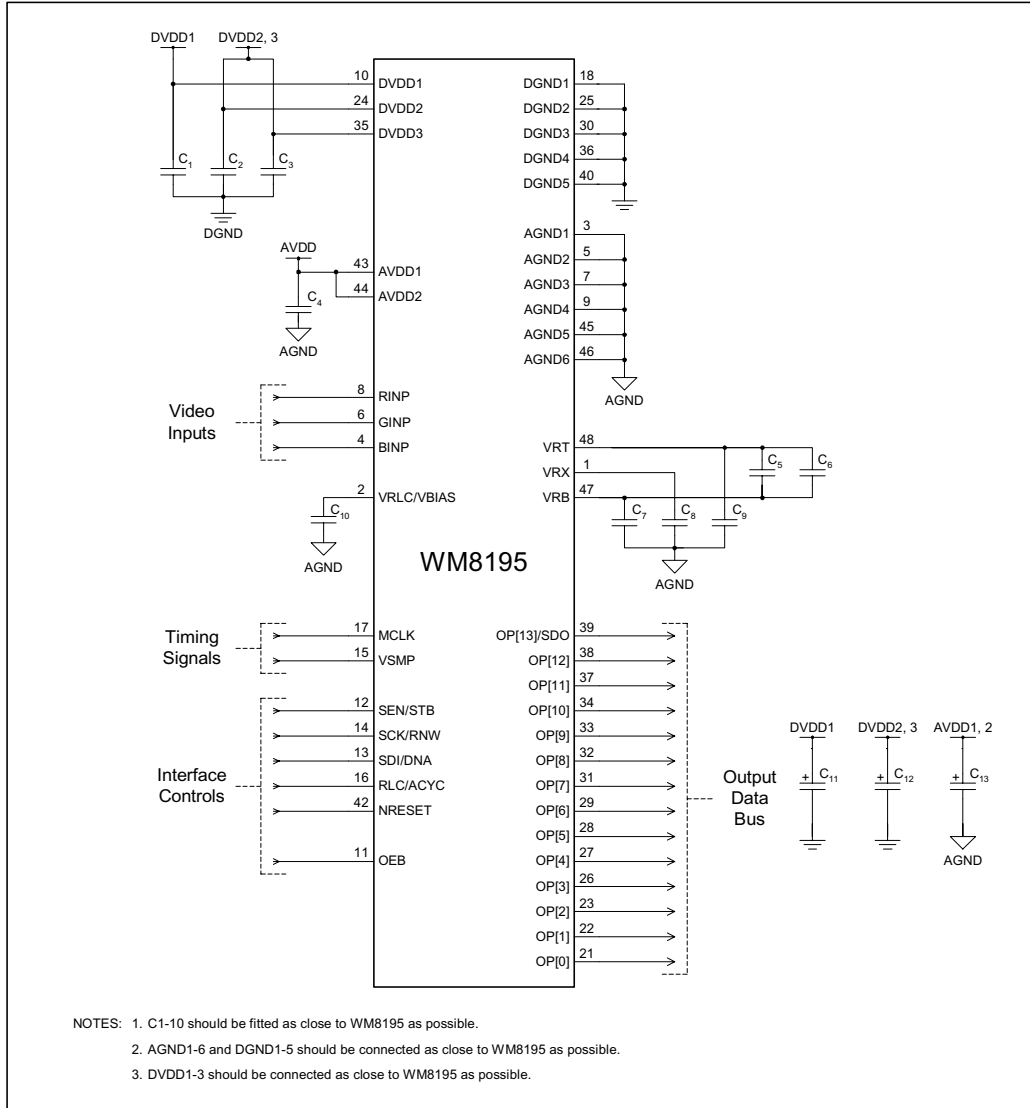
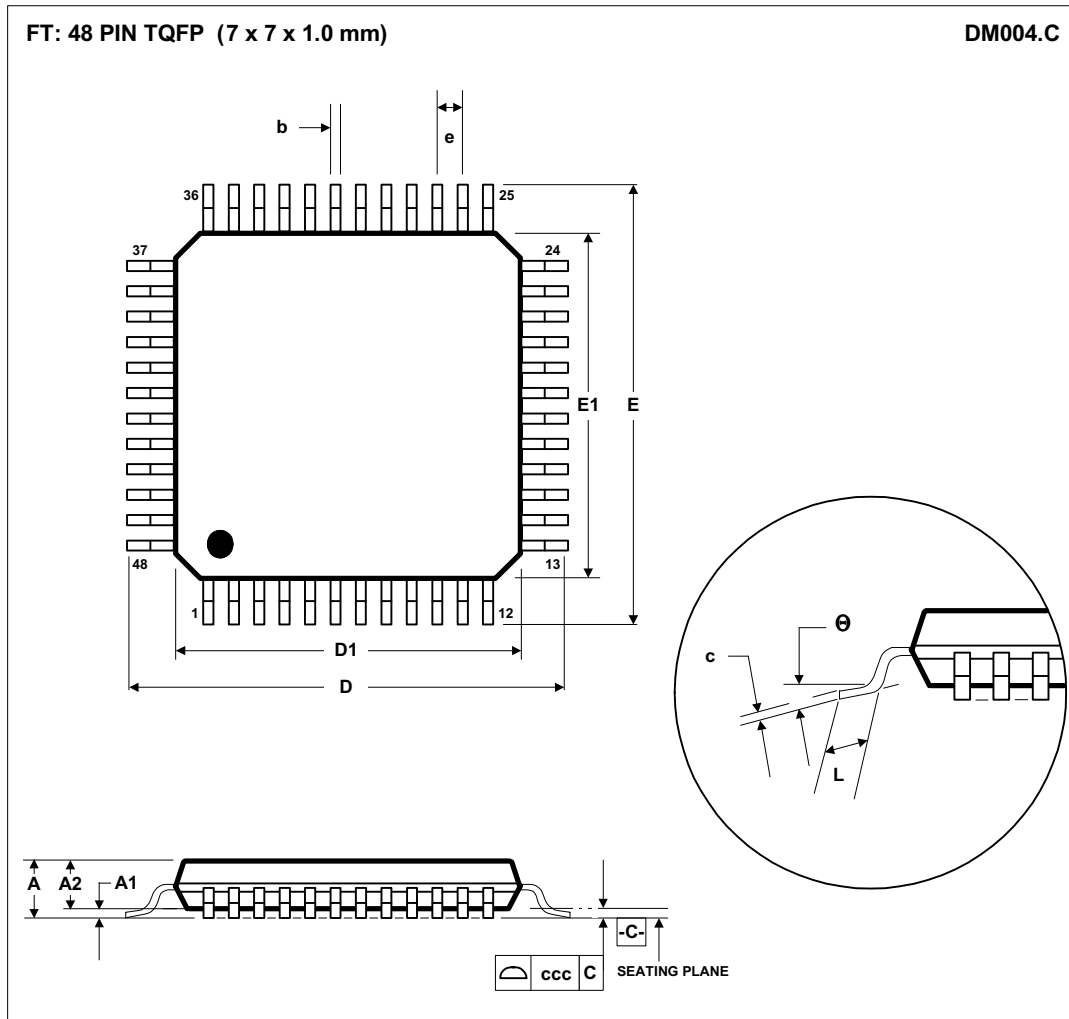


Figure 27 External Components Diagram

COMPONENT REFERENCE	SUGGESTED VALUE	DESCRIPTION
C1	100nF	De-coupling for DVDD1.
C2	100nF	De-coupling for DVDD2.
C3	100nF	De-coupling for DVDD3.
C4	100nF	De-coupling for AVDD1 and AVDD2.
C5	10nF	High frequency de-coupling between VRT and VRB.
C6	1µF	Low frequency de-coupling between VRT and VRB (non-polarised).
C7	100nF	De-coupling for VRB.
C8	100nF	De-coupling for VRX.
C9	100nF	De-coupling for VRT.
C10	100nF	De-coupling for VRLC.
C11	1µF	Reservoir capacitor for DVDD1.
C12	1µF	Reservoir capacitor for DVDD2 and DVDD3.
C13	1µF	Reservoir capacitor for AVDD1 and AVDD2.

Table 8 External Components Descriptions

PACKAGE DIMENSIONS



Symbols	Dimensions (mm)		
	MIN	NOM	MAX
A	-----	-----	1.20
A ₁	0.05	-----	0.15
A ₂	0.95	1.00	1.05
b	0.17	0.22	0.27
c	0.09	-----	0.20
D	9.00 BSC		
D ₁	7.00 BSC		
E	9.00 BSC		
E ₁	7.00 BSC		
e	0.50 BSC		
L	0.45	0.60	0.75
θ	0°	3.5°	7°
Tolerances of Form and Position			
ccc	0.08		
REF:	JEDEC.95, MS-026		

NOTES:
 A. ALL LINEAR DIMENSIONS ARE IN MILLIMETERS.
 B. THIS DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE.
 C. BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSION, NOT TO EXCEED 0.25MM.
 D. MEETS JEDEC.95 MS-026, VARIATION = ABC. REFER TO THIS SPECIFICATION FOR FURTHER DETAILS.

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